

Title (en)
MINIATURE CIRCUITRY AND INDUCTIVE COMPONENTS AND METHODS FOR MANUFACTURING SAME

Title (de)
MINIATURSCHALTKREISE UND INDUKTIVE KOMPONENTEN UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
CIRCUIT MINIATURE ET COMPOSANTS D'INDUCTEURS, ET PROCÉDÉS DE FABRICATION ASSOCIÉS

Publication
EP 1861857 A4 20090902 (EN)

Application
EP 05853280 A 20051207

Priority
• US 2005044319 W 20051207
• US 63374204 P 20041207

Abstract (en)
[origin: WO2006063081A2] Miniature circuitry and inductor components in which multiple levels of printed circuitry are formed on each side of a support panel, typically a printed circuit board or rigid flex. Electrical connection between the plural levels of circuitry and multiple windings around magnetic members are provided by plural plated through hole conductors. Small through hole openings accommodate a plurality of the plated through hole conductors since each is insulated from the others by a very thin layer of vacuum deposited organic layer such as parylene having a high dielectric strength. Adhesion of this plated copper to the organic layer is provided by first applying an adhesive promotor to the surface of the organic layer followed by the vacuum deposition of the organic layer.

IPC 8 full level
H01F 27/28 (2006.01)

CPC (source: EP KR US)
H01F 5/00 (2013.01 - KR); **H01F 17/0033** (2013.01 - EP US); **H01F 27/266** (2013.01 - EP US); **H01F 27/2804** (2013.01 - EP US); **H01F 41/046** (2013.01 - EP US); **H01L 27/04** (2013.01 - KR); **H05K 1/165** (2013.01 - EP US); **H05K 3/429** (2013.01 - EP US); **H01F 17/062** (2013.01 - EP US); **H01F 19/04** (2013.01 - EP US); **H01F 2017/002** (2013.01 - EP US); **H05K 1/189** (2013.01 - EP US); **H05K 3/389** (2013.01 - EP US); **H05K 3/4644** (2013.01 - EP US); **H05K 2201/0179** (2013.01 - EP US); **H05K 2201/086** (2013.01 - EP US); **H05K 2201/097** (2013.01 - EP US); **H05K 2201/09809** (2013.01 - EP US); **H05K 2201/10416** (2013.01 - EP US); **Y10T 29/49124** (2015.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/49155** (2015.01 - EP US); **Y10T 29/49156** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US)

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Designated contracting state (EPC)
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DOCDB simple family (publication)
WO 2006063081 A2 20060615; WO 2006063081 A3 20071206; AU 2005314077 A1 20060615; AU 2005314077 B2 20100805; CA 2589485 A1 20060615; CN 101151688 A 20080326; CN 101151688 B 20130116; EP 1861857 A2 20071205; EP 1861857 A4 20090902; HK 1114464 A1 20081031; JP 2008523627 A 20080703; KR 101165116 B1 20120712; KR 20070095885 A 20071001; MX 2007006737 A 20071123; RU 2007120247 A 20090120; TW 200638446 A 20061101; TW I416557 B 20131121; US 2006152322 A1 20060713; US 2007294888 A1 20071227; US 2008017404 A1 20080124; US 2010146782 A1 20100617; US 7271697 B2 20070918; US 7602272 B2 20091013; US 7690110 B2 20100406

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